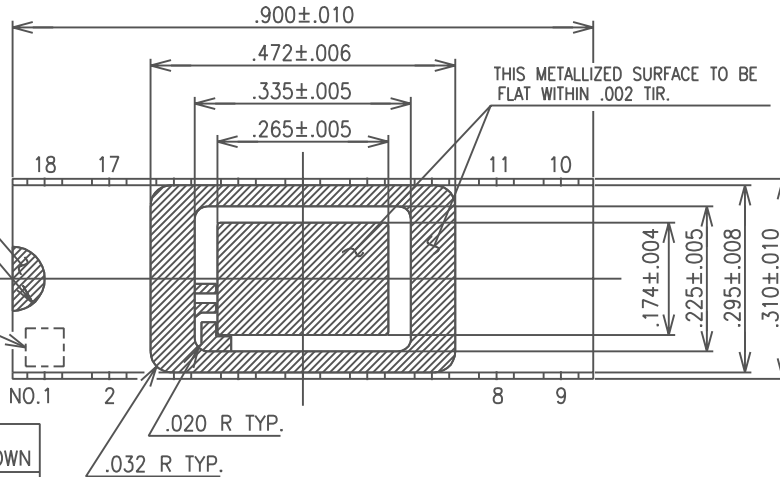
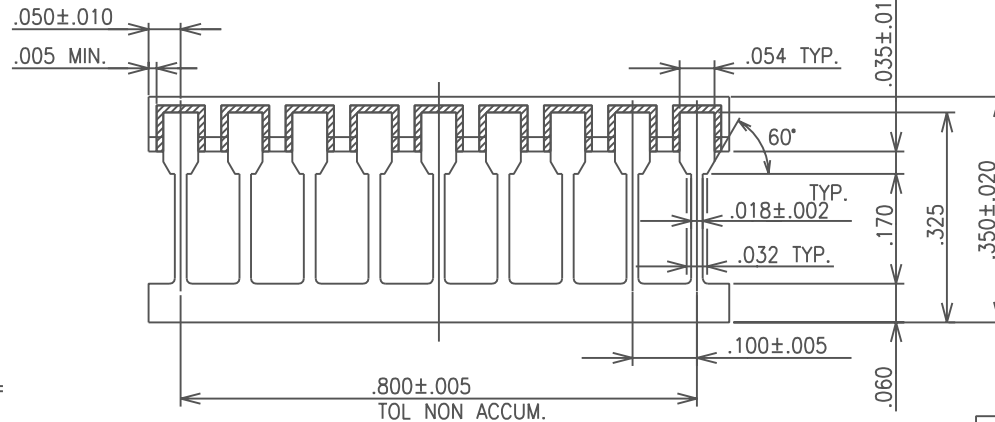


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD (PART NO.01 ONLY)

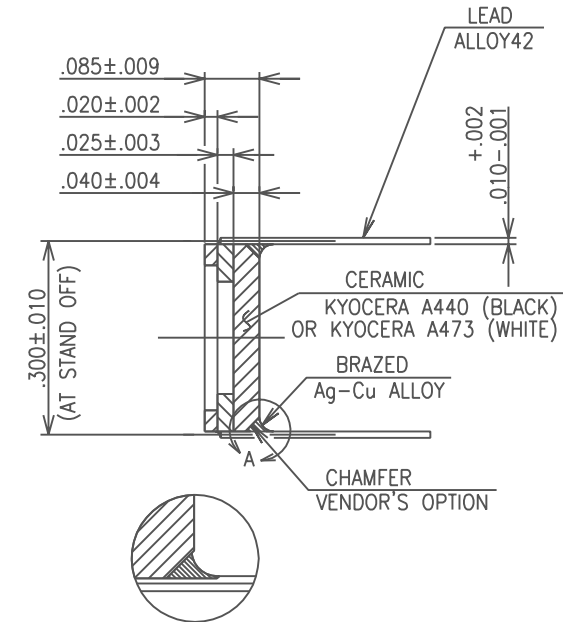
.050R NOTCH
INDEX MARK (SEE TABLE)



| PART NO. | INDEX MARK | LEAD TIED DOWN |
|----------|------------|----------------|
| 01 | | NIL |
| 02 | | NO.1 ONLY |



VENDOR'S OPTION



DETAIL-A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.10 OHM MAX. AT PIN NO.9,18 OTHER LESS THAN 0.20 OHM MAX.

SB018H032-2 ^{S=0}/_{D=1} SB018H032-1 ^{S=0}/_{D=0}

| | | | | | | | | | | | | |
|--------------|--|-------------------------------|-----------------|------------|-------|---------|-------------------------------------|---|------------------------------------|----------------|---------------------------|--------------------|
| MODIFICATION | | | | | | | NAME 18 LEAD SIDE BRAZED PACKAGE | TOLERANCE UNLESS OTHERWISE SPECIFIED | DRAWN M.K | CHECKED K.M | APPROVED | DATE FEB.18.'77 |
| | | | | | | | SCALE 5/1 | MATERIAL AS INDICATED | ±.005 | | | |
| | | | | | | | | THIRD ANGLE PROJECTION | | | | |
| | | REDRAWN: (CONVERTED CAD DATA) | ADDED:SHEET 2/2 | OCT.20.'94 | K.I | T.C/S.F | T.A | | KYOCERA CORPORATION KYOTO JAPAN | | DRAWING NO. KD-77032-G | SHEET 1/2 |
| | | CHANGED | | DATE | DRAWN | CHECKED | APPROVED | | | | | |



